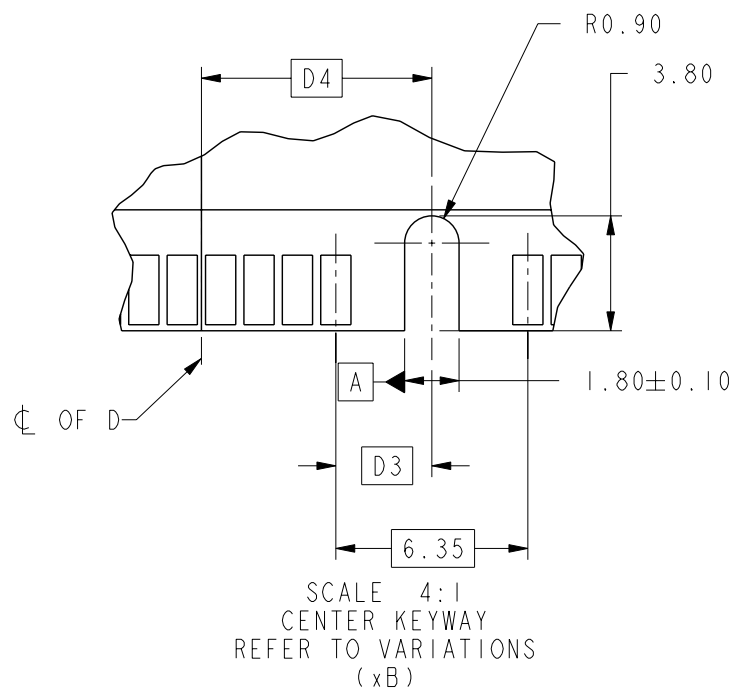
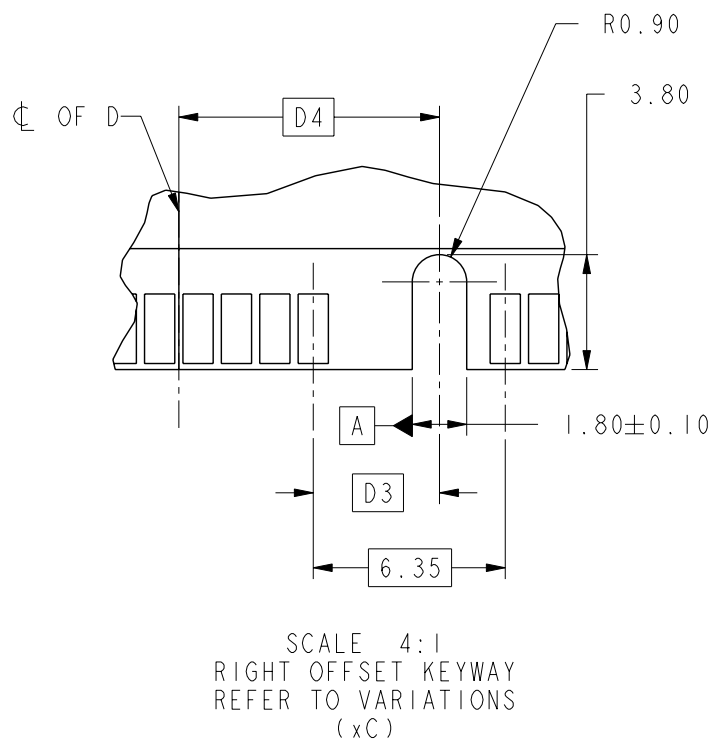
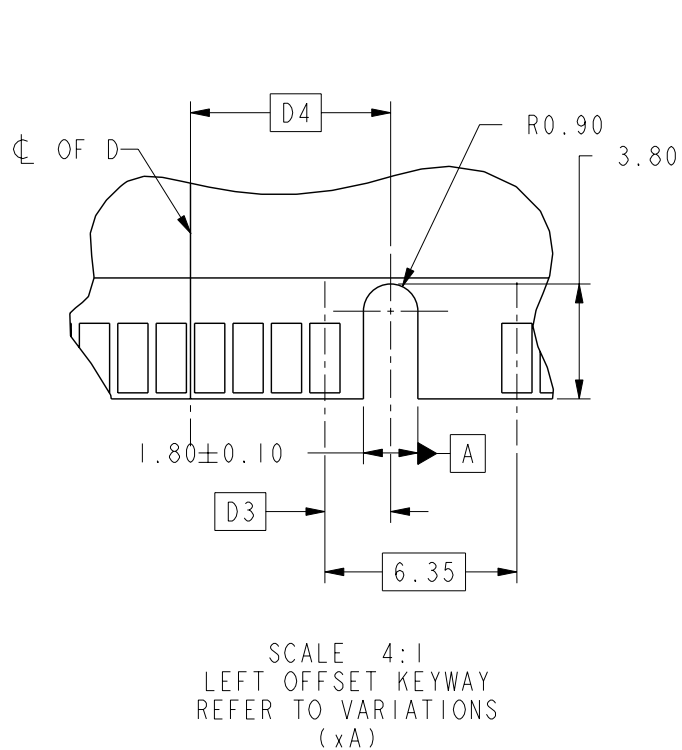


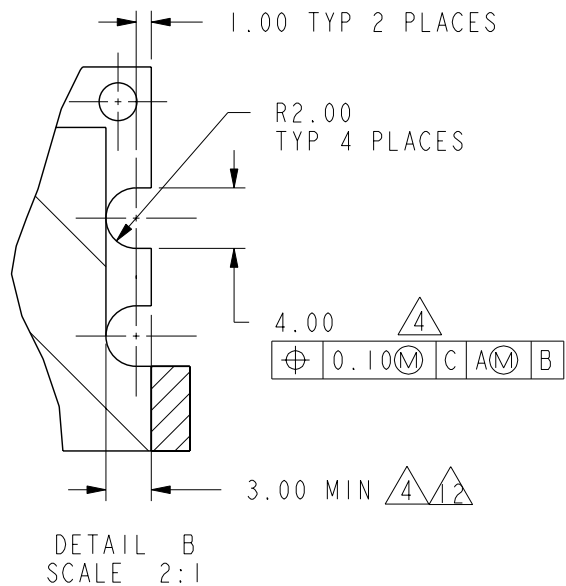
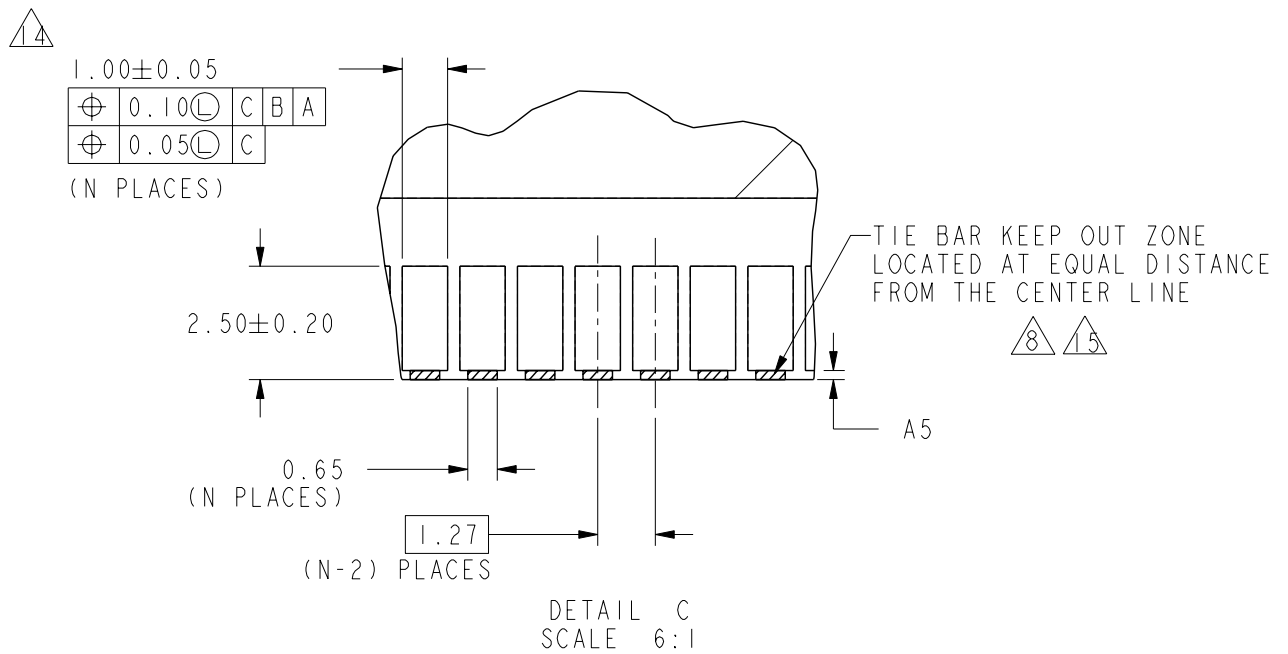
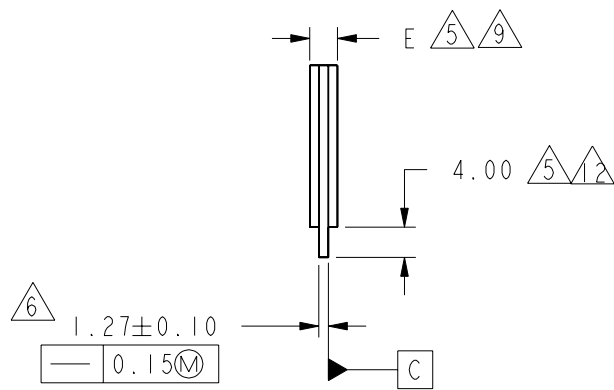
JEDEC SOLID STATE PRODUCT OUTLINE	THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.				
TITLE DUAL INLINE MEMORY MODULE (DIMM) FAMILY 184 PIN DDR 1.27mm CONTACT CENTERS	DESIGNATOR	ISSUE A	DATE AUG 1998	ITEM MO-206	SHEET 1 OF 5



DETAIL A









JEDEC SOLID STATE PRODUCT OUTLINE	TITLE DUAL INLINE MEMORY MODULE (DIMM) FAMILY 184 PIN DDR 1.27mm CONTACT CENTERS	ISSUE A	DATE AUG 1998	ITEM MO-206	SHEET 2 OF 5
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JEDEC SOLID STATE PRODUCT OUTLINE	TITLE DUAL INLINE MEMORY MODULE (DIMM) FAMILY 184 PIN DDR 1.27mm CONTACT CENTERS	ISSUE A	DATE AUG 1998	ITEM MO-206	SHEET 3 OF 5
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184-PIN DDR DIMM VARIATIONS

	AA 			AB 			AC 			NOTES
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	
A	25.25	25.40	25.55	25.25	25.40	25.55	25.25	25.40	25.55	
A1	2.30BSC			2.30BSC			2.30BSC			
A2	10.00BSC			10.00BSC			10.00BSC			
A3	17.80BSC			17.80BSC			17.80BSC			
A4	19.80BSC			19.80BSC			19.80BSC			
A5	0.05	0.20	0.35	0.05	0.20	0.35	0.05	0.20	0.35	
D	138.30	138.45	138.60	138.30	138.45	138.60	138.30	138.45	138.60	13
D1	133.20	133.35	133.50	133.20	133.35	133.50	133.20	133.35	133.50	
D2	128.95BSC			128.95BSC			128.95BSC			
D3	2.175BSC			3.175BSC			4.175BSC			11
D4	6.62BSC			7.62BSC			8.62BSC			
E	-	-	9.00	-	-	9.00	-	-	9.00	5,9
e1	64.77BSC			64.77BSC			64.77BSC			
e2	49.53BSC			49.53BSC			49.53BSC			
N	184			184			184			7
ISSUE										
REF										
NOTES	1,3			1,3			1,3			

	BA 			BB 			BC 			NOTES
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	
A	31.60	31.75	31.90	31.60	31.75	31.90	31.60	31.75	31.90	
A1	2.30BSC			2.30BSC			2.30BSC			
A2	10.00BSC			10.00BSC			10.00BSC			
A3	17.80BSC			17.80BSC			17.80BSC			
A4	19.80BSC			19.80BSC			19.80BSC			
A5	0.05	0.20	0.35	0.05	0.20	0.35	0.05	0.20	0.35	
D	138.30	138.45	138.60	138.30	138.45	138.60	138.30	138.45	138.60	13
D1	133.20	133.35	133.50	133.20	133.35	133.50	133.20	133.35	133.50	
D2	128.95BSC			128.95BSC			128.95BSC			
D3	2.175BSC			3.175BSC			4.175BSC			11
D4	6.62BSC			7.62BSC			8.62BSC			
E	-	-	9.00	-	-	9.00	-	-	9.00	5,9
e1	64.77BSC			64.77BSC			64.77BSC			
e2	49.53BSC			49.53BSC			49.53BSC			
N	184			184			184			7
ISSUE										
REF										
NOTES	1,3			1,3			1,3			

NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994
- 2 TOLERANCES ON ALL DIMENSIONS ± 0.13 UNLESS OTHERWISE SPECIFIED.
- 3 ALL DIMENSIONS ARE IN MILLIMETERS.
- 4 3.00 mm MINIMUM APPLIES TO BOTH 4.00 mm WIDE NOTCH LENGTH AND BORDER OF THE COMPONENT KEEPOUT AREA.
- 5 DIMENSION APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDES OR ONE SIDE OF MODULE.
- 6 CARD THICKNESS APPLIES ACROSS THE CONTACTS AND INCLUDES PLATING AND/OR METALIZATION. STRAIGHTNESS CALLOUT APPLIES TO ZONE DEFINED BY THE 4.00 CONTACT AREA DIMENSION FOR THE ENTIRE LENGTH OF 133.35.
- 7 N IS THE TOTAL NUMBER OF CIRCUIT CONTACTS (PINS, LEADS, TABS, OR PADS).
- 8 LEADING EDGE OF CONTACT PADS SPECIFIED BY THE KEEP OUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.
- 9 WHEN SOJ DEVICES ARE USED FOR ASSEMBLY OF THIS MODULE, THE MAXIMUM THICKNESS OVERALL SHALL NOT EXCEED 9.00 mm. WHEN TSOP DEVICES ARE USED, THE MAXIMUM THICKNESS SHALL NOT EXCEED 3.67 mm.
- 10 VARIATIONS IN A (HEIGHT) AND D3 (VOLTAGE) FOR EXAMPLE, VARIATION AA DENOTES 25.40 HEIGHT AND 2.5 VOLTS.
- 11 THE JC-42.5 COMMITTEE CONTROLS THIS INFORMATION. IT IS SHOWN HERE FOR REFERENCE ONLY, AND IS SUBJECT TO CHANGE. XA = 2.5 VOLTS; XB = 1.8 VOLT; XC = TBD VOLTS
- 12 BORDER OF COMPONENT KEEPOUT AREA.
- 13 WHEN OPTIONAL EARS EXIST "D" IS CONTROLLING AND WHEN OPTIONAL EARS DO NOT EXIST "D" DOES NOT APPLY.

APPLICATION NOTES:

- 14 OPTION 1 - PREFERABLE PLATING. ELECTROLYTIC GOLD PLATING 0.76 MICROMETERS MINIMUM OVER ELECTROLYTIC Ni 2.0 MICROMETERS MIN. OPTION 2 - ALTERNATE PLATING. GOLD PLATING 0.05-0.75 MICROMETERS OVER Ni 2.0 MICROMETERS MINIMUM MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT.
- 15 FOR OPTIMUM PERFORMANCE, THE TIE BAR IS TO BE ON AN INTERNAL LAYER, SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE DUAL INLINE MEMORY MODULE (DIMM) FAMILY 184 PIN DDR 1.27mm CONTACT CENTERS	ISSUE A	DATE AUG 1998	ITEM MO-206	SHEET 5 OF 5
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